

ENSC Batch No. _____ Wafers Started _____ Date _____
 Material _____ Orientation _____ Size _____ Thickness _____
 Resistivity _____ Type _____
 Wafer Vendor _____ Vendor Batch # _____ SFU P.O. _____

Process Step #	Process Conditions	Oper & Wafer #	Comments
			RCA clean all wafers immediately before placing in furnace. Also note O2 is not used in this oxidation
___ A	Prepare Furnace (Tube 1) N2 at 4 scfh. O2 at 0. Ramp to 800C. Fill bubbler with DI water. Start water heater and tape heaters.		
___ B	Load Wafers into Boat Use correct boat and white elephant. Use wafer forceps		
___ C	Push Boat into Furnace Use gloves and quartz rod. Push (< 4 in/min) when all zones <800C		
___ D	Ramp Furnace Up Set oper temp (typ 1000-1100) Dry N2 @4 scfh		
___ E	Wet Oxidation Tube at temp. N2 into bubbler at 4 scfh. for good action in bubbler. Variac at 100/140 Set timer. Open stopcock.		Time = _____ min. Temp = _____ C Desired thickness = _____ microns Set time and temp according to curves for desired thickness.
___ F	Ramp Furnace Down Close stopcock.. Dry N2 at 4 scfh, Set Temp 800/400 C.		
___ G	Pull Boat and Unload Use gloves and quartz rod. Pull out (< 4 in/min) when all zones <800C. Dry N2 at 4 scfh		
___ H	Return Furnace to Idle N2 at 0.5-1.0 scfh.		
___ I	Inspect Colour, ellipsometer, etc.		